

ABSTRACT OF THE DISCLOSURE

In a substrate cleaning device, a substrate is held and is opposite to a plurality of heating/cooling components that can operate at different temperatures, the substrate and the heating/cooling components being
5 separated to each other with a gap, which is filled with cleaning liquid. Chuck pins of resin with a low heat conductivity are used to hold the substrate, and the substrate is positioned such that it is not in contact with any component other than the chuck pins. In this way, the amount of
10 etching can be adjusted for each portion of the substrate by controlling the temperature distribution on the substrate, thereby providing improved evenness of a surface within the plane of the substrate after a cleaning process.